

Film Frame Tape Applicator Operation

Operation

1. If your process requires that the chuck be heated, set the heater controller to the desired temperature by:

- a. Press the enter button , the display will now show the current setpoint in the top field and SP in the bottom field.



- b. Use the arrow up/down keys to adjust the temperature.
- c. Press the enter key again to register the new value.

NOTE: If you are dicing down to a die size 5 mm or less, it is recommended to heat the chuck. The tape manufacturer's recommended chuck temperature is 40°C with no dwell time.

2. Raise the cutter cover.
3. Place the film frame on platen and up against frame locating pins. Magnets will hold it in place.
4. Place your substrate face down on the chuck. Use the markings on the chuck to center and align your substrate.
5. Move the WAFER VACUUM switch up to the ON position.
6. Carefully remove the tape from the rear tensioner bar, pull it forward to the front tensioner bar and lay it onto the bar. It is recommended to lightly adhere tape to the front tensioner bar.
7. Press and hold the MOTOR ON/OFF button to retract the protective film. Release the button right as the protective film clears the rear tensioner bar.
8. Swing the roller assembly up into track and uniformly roll it across wafer/film frame and back to the forward location. You do not need to press down on the roller while you do this.
9. Close the cutter cover.
10. Push down on the circular cutter handle and rotate it in a full circle. Make sure to go around a little more than one full rotation, multiple rotations are not needed and will only cause unnecessary blade wear.
11. Position the end cutter over the tape, press the end cutter down, and slide it back and forth across width of tape once.
12. Raise cutter cover, remove the excess tape and turn off the wafer vacuum.
13. Remove the finished film frame assembly.